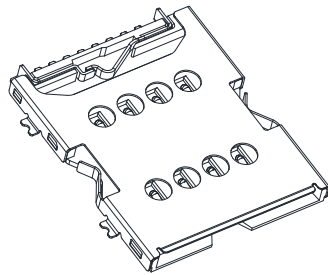




**ALTERNATIVE
COMPONENT
SOURCE**

a Major League Electronics Company

2533 Centennial Blvd. Jeffersonville, Indiana, USA 47130



TECHNICAL CHARACTERISTICS

1. General Characteristics

Dimension: 18.80L x 15.85W x 1.70H mm

Weight: Approx. 0.63 g

Contact principle: Friction technology

Operating position: Shaft up / Down / Horizontal

Mounting System: SMT Type (without post)

Function: With Tray Type (Tray exclude)

Durability: 5,000 cycles min.

2. Mechanical Characteristics

Insulation material: Thermoplastic, UL 94V-0

RoHS Directive 2011/65/EU Compliant

3. Electrical Characteristics

Number of contacts: 8 pins

Contact resistance: 50 mΩ typical, 100 mΩ max.

Insulation resistance: >1000 MΩ / 500 VDC

Switch type: Blade

Operation: Normally Close

4. Solderability

Wave: Not applicable

IR reflow: 260C, 10 sec. Max.

Manual soldering: 360C, 3 sec. Max.

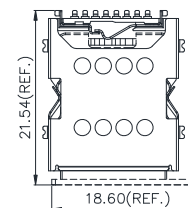
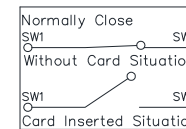
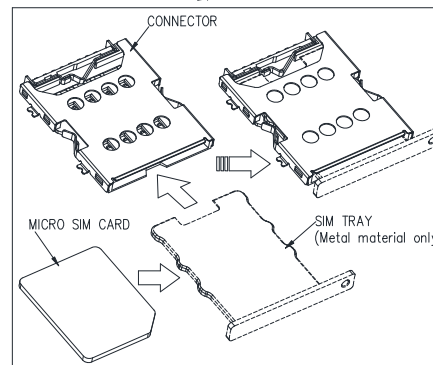
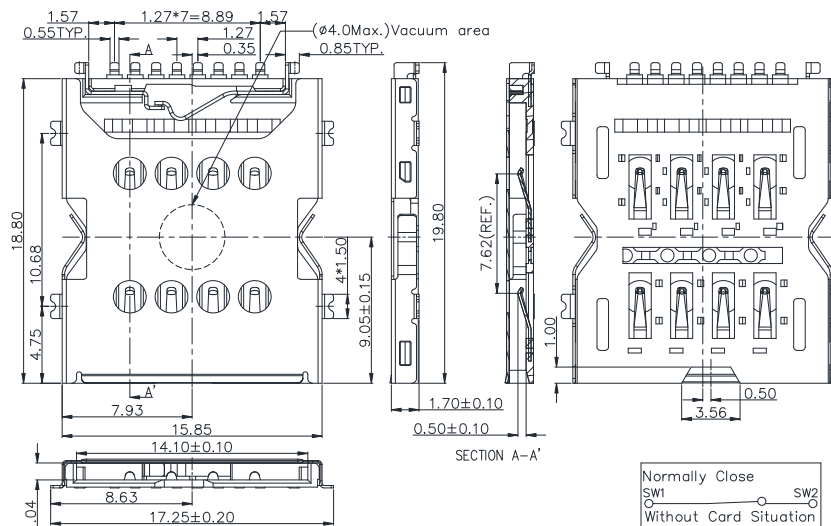
5. Environmental Characteristics

Operating temperature: - 40C ~ + 85C

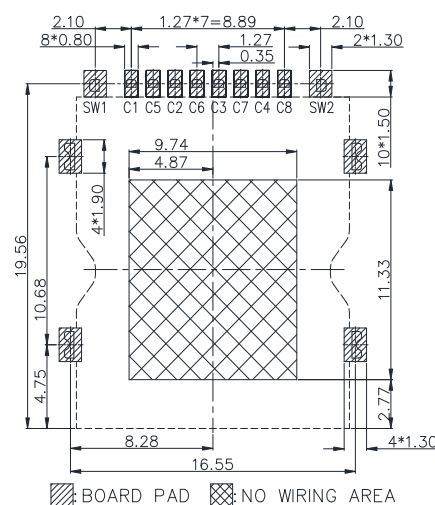
Operating humidity: 10 % ~ 95 % RH

Storage temperature: - 40C ~ + 85C

Storage humidity: 10 % ~ 95 % RH



Unit: mm; Tolerances: 0.15 mm
Mechanical outline dimension



Unit: mm; Tolerances: 0.05 mm
Reference dimension for PCB layout

Micro SIM Card Connector

Model No.: ICC-M03

Revision: 1.1

Date: MAY 01, 2014

Note:

1. Coplanarity of solder pins 0.10mm max.

2. Recommended thickness of solder paste > 0.15mm.